

902 Series

Wakefield-Vette's 900 Series Heat Sinks for Chipset can match up to devices from Intel, Broadcom, Xilinx, TI, Motorola, ATI, AMD, Nvidia, Vishay, Powerex, Infineon, Microsemi, and many more.

These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, Cloud Computing, and many more Industries.

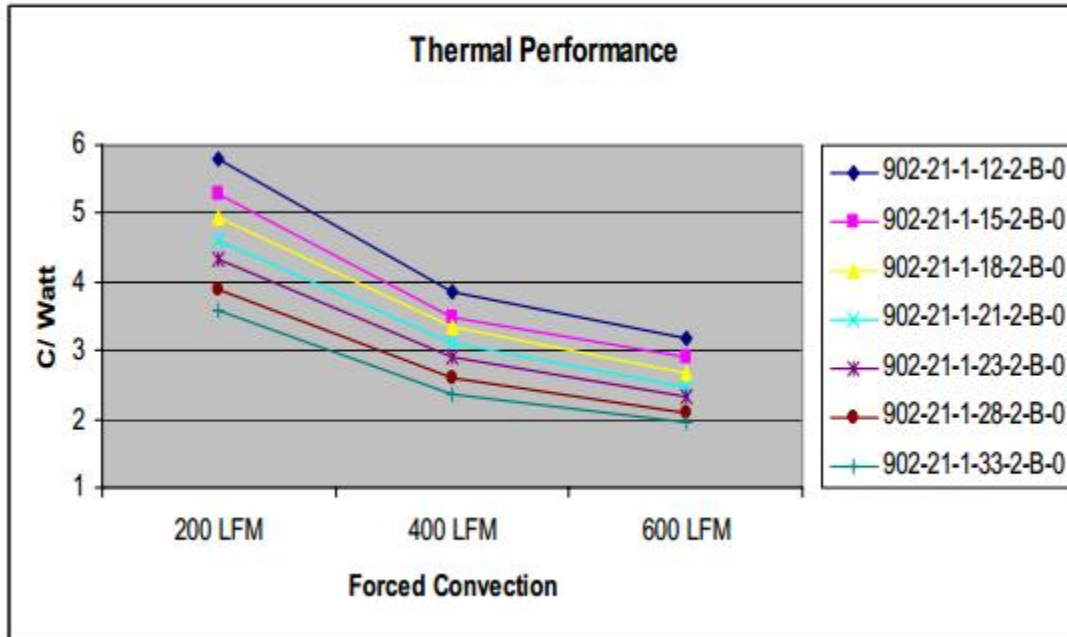
Material: AL 6063

Finish: Black Anodize

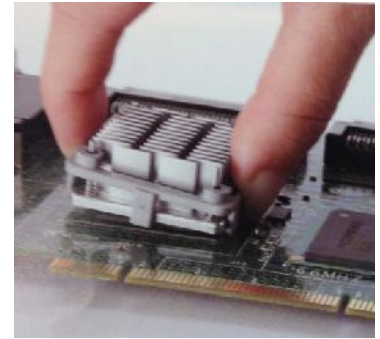
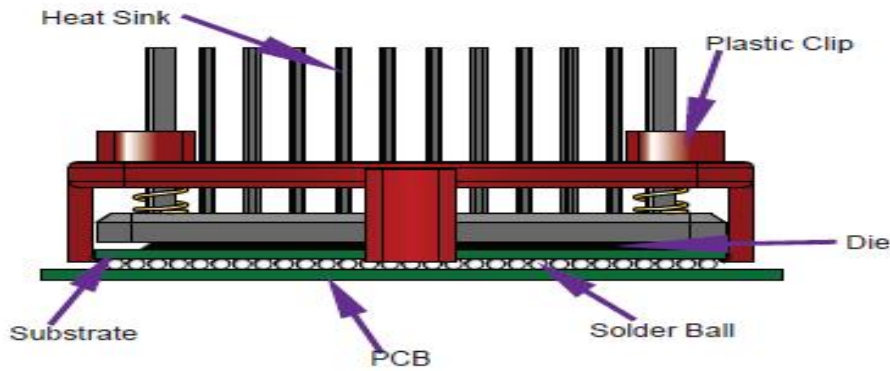


PART #	HEIGHT (mm)	CHIP SIZE (mm)	NATURAL CONVECTION	FORCED CONVECTION (C/W)		
				200 LFM	400 LFM	600 LFM
902-21-1-12-2-B-0	12	21	14.31 C/W	5.81 C/W	3.86 C/W	3.16 C/W
902-21-1-15-2-B-0	15	21	13.57 C/W	5.3 C/W	3.5 C/W	2.89 C/W
902-21-1-18-2-B-0	18	21	12.83 C/W	4.95 C/W	3.35 C/W	2.66 C/W
902-21-1-21-2-B-0	21	21	12.09 C/W	4.61 C/W	3.111 C/W	2.47 C/W
902-21-1-23-2-B-0	23	21	11.63 C/W	4.32 C/W	2.91 C/W	2.32 C/W
902-21-1-28-2-B-0	28	21	10.47 C/W	3.89 C/W	2.61 C/W	2.09 C/W
902-21-1-33-2-B-0	33	21	9.3 C/W	3.57 C/W	2.37 C/W	1.95 C/W

THERMAL PERFORMANCE:

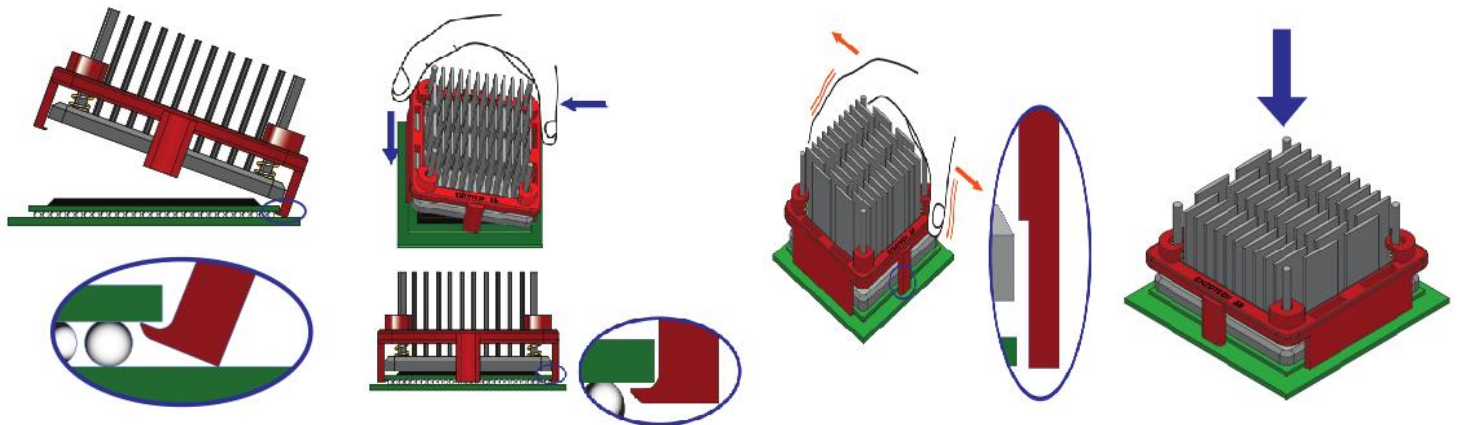


Series	Chip Size	Construction	Height	Chip Height	Finish	Interface
902-	19-	1-	12-	1-	B = BLK ANO	1
	19	1 = Elliptical Fin	12 = 11.6	1 = .9-2.1		
	21		15 = 14.6	2 = 2.2-3.4		
	23		18 = 17.6			
	27		21 = 20.6			
	29		23 = 22.6			
	31		28 = 27.6			
	33		33 = 32.6			
	35					
	37.5					
40						



Wakefield-Vette's heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.

ASSEMBLY INSTRUCTION:



Step 1: Hook the clip under one side of the BGA chip set.

Step 2: Rotate assembly down until opposite side clip engages substrate edge of BGA chip set.

Step 3: Make sure the solder rods are clearing from edges of BGA chip set.

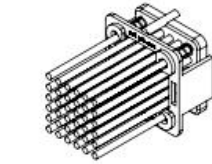
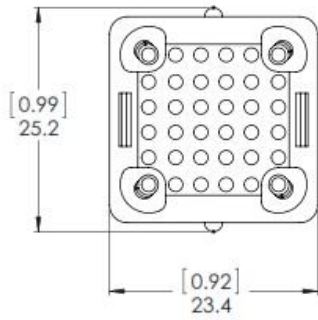
Step 4: Press firmly down to make sure clips fully engage edges of chip set. Heat Sink should not move around easily.

Random Vibration Test

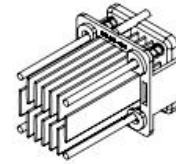
Frequency : 5 Hz to 500 Hz
 Acceleration : 3.13 grms
 P.S.D : 0.01 g²/HZ (5 Hz)
 0.02 g²/HZ (20 Hz to 500 Hz)
 Test Axis : X, Y, Z axis
 Test Time : 10 mins (Each axis)
 Total Test Time : 30 mins

SHOCK TEST SPECIFICATION :

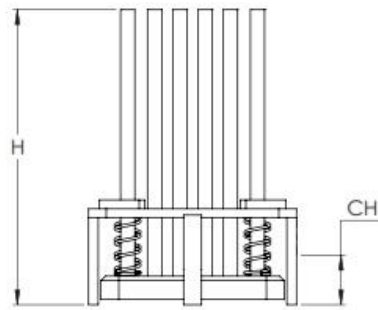
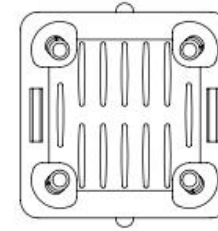
Wave Form : Half sine wave
 Acceleration : 50 g
 Duration Time : 11 ms
 No. of Shock : Each axis 3 times
 Shock Direction : ±X, ±Y, ±Z axis
 Reliability & Communication
 Testing Instruments



CONSTRUCTION CODE- 2
PIN FINS
6 X 6 PIN ARRAY =
36 FINS, 1.6 mm DIA.

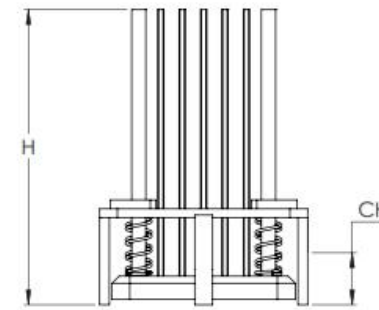


CONSTRUCTION CODE- 1
ELLIPTICAL FINS
12 FINS, 7.2 Lg X 0.7 W mm
4 CORNER PIN FINS



HEIGHT (H) CODE	ACTUAL mm
12-	11.6
15-	14.6
18-	17.6
21-	20.6
23-	22.6
28-	27.6
33-	32.6

CHIP HEIGHT (CH) CODE	ACTUAL RANGE mm
1-	0.9 to 2.1
2-	2.2 to 3.4



902 SERIES FOR 21mm CHIPS

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MATERIAL: 6063-T5 AL ALLOY		APPROVALS: _____ DATE: 10/21/2014 DRAWN: _____		DRAWING NOT TOSCALE		DESCRIPTION: CHIPSET HEAT SINKS	
FINISH: BLACK ANODIZE		CHK: _____ DSGN ENG: 10/21/2014 MFG ENG: _____ QA: _____		REVISION: _____ SCALE: 2:1		DWG. NO. 902 Series 1 OF 1	
SH_SIZE: B		MODEL INFO: MBA21052-no lip					